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(12) **United States Design Patent**  
**Andre et al.**

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(54) **THERMAL DEVICE**  
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(73) Assignee: **Apple Inc.**, Cupertino, CA (US)

(\*\*) Term: **14 Years**

(21) Appl. No.: **29/510,950**

(22) Filed: **Dec. 4, 2014**

**Related U.S. Application Data**

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(51) **LOC (10) Cl.** ..... **13-03**

(52) **U.S. Cl.**  
USPC ..... **D13/179; D23/370**

(58) **Field of Classification Search**  
USPC ..... D13/179; D23/370, 379  
CPC . F04D 25/062; F04D 29/4206; F04D 29/601;  
F04D 29/626; H01L 23/3672; H01L 21/3677;  
H01L 21/467; Y10T 29/49243; Y10T  
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See application file for complete search history.

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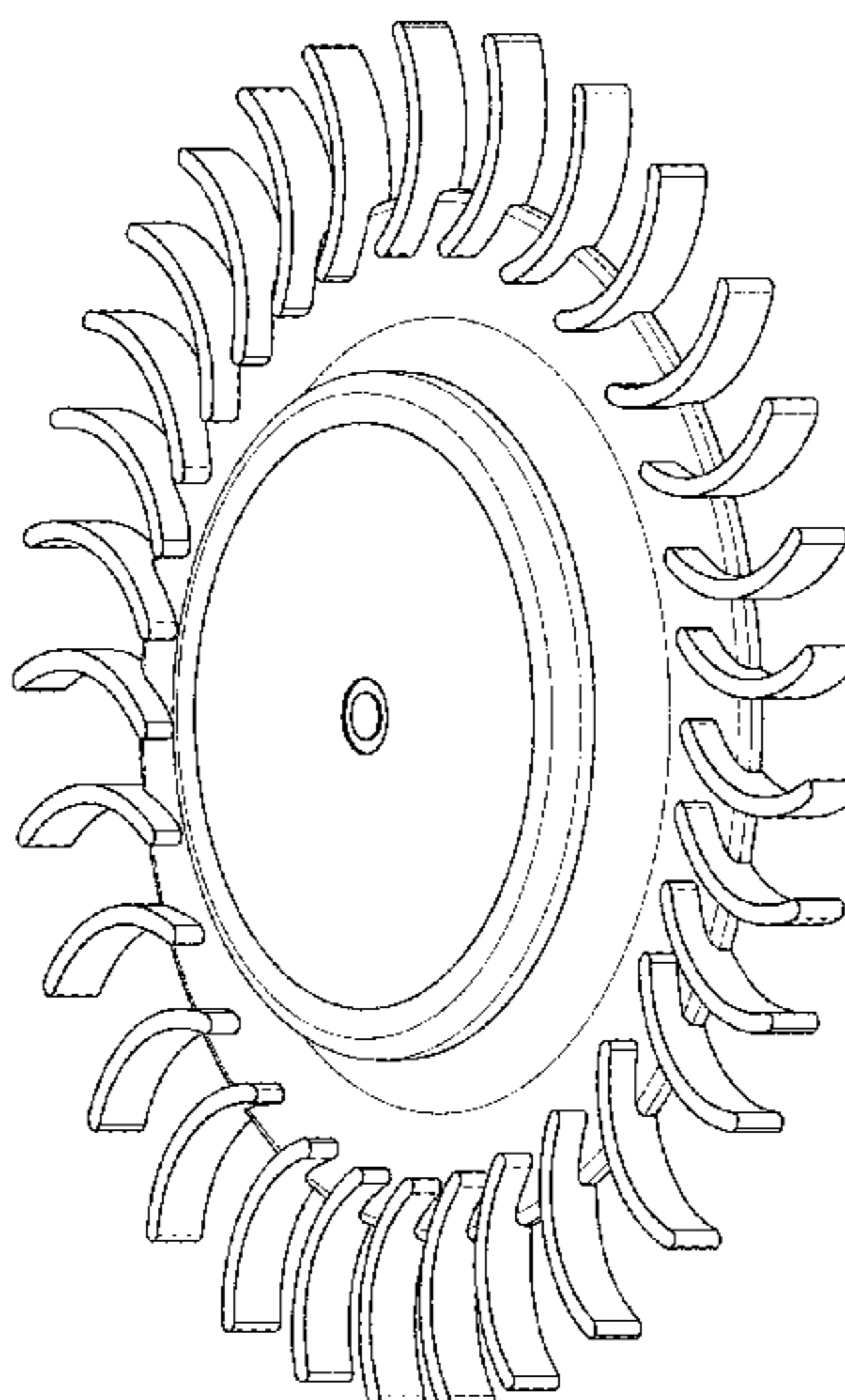
(57) **CLAIM**

The ornamental design for a thermal device, as shown and described.

**DESCRIPTION**

FIG. 1 is a front perspective view of a thermal device showing our new design;  
FIG. 2 is a rear perspective view thereof;  
FIG. 3 is a front view thereof;  
FIG. 4 is a rear view thereof;  
FIG. 5 is a left side view thereof;  
FIG. 6 is a right side view thereof;  
FIG. 7 is a top view thereof; and,  
FIG. 8 is a bottom view thereof.  
The drawings include CAD lines that represent contour and not surface decoration.

**1 Claim, 5 Drawing Sheets**



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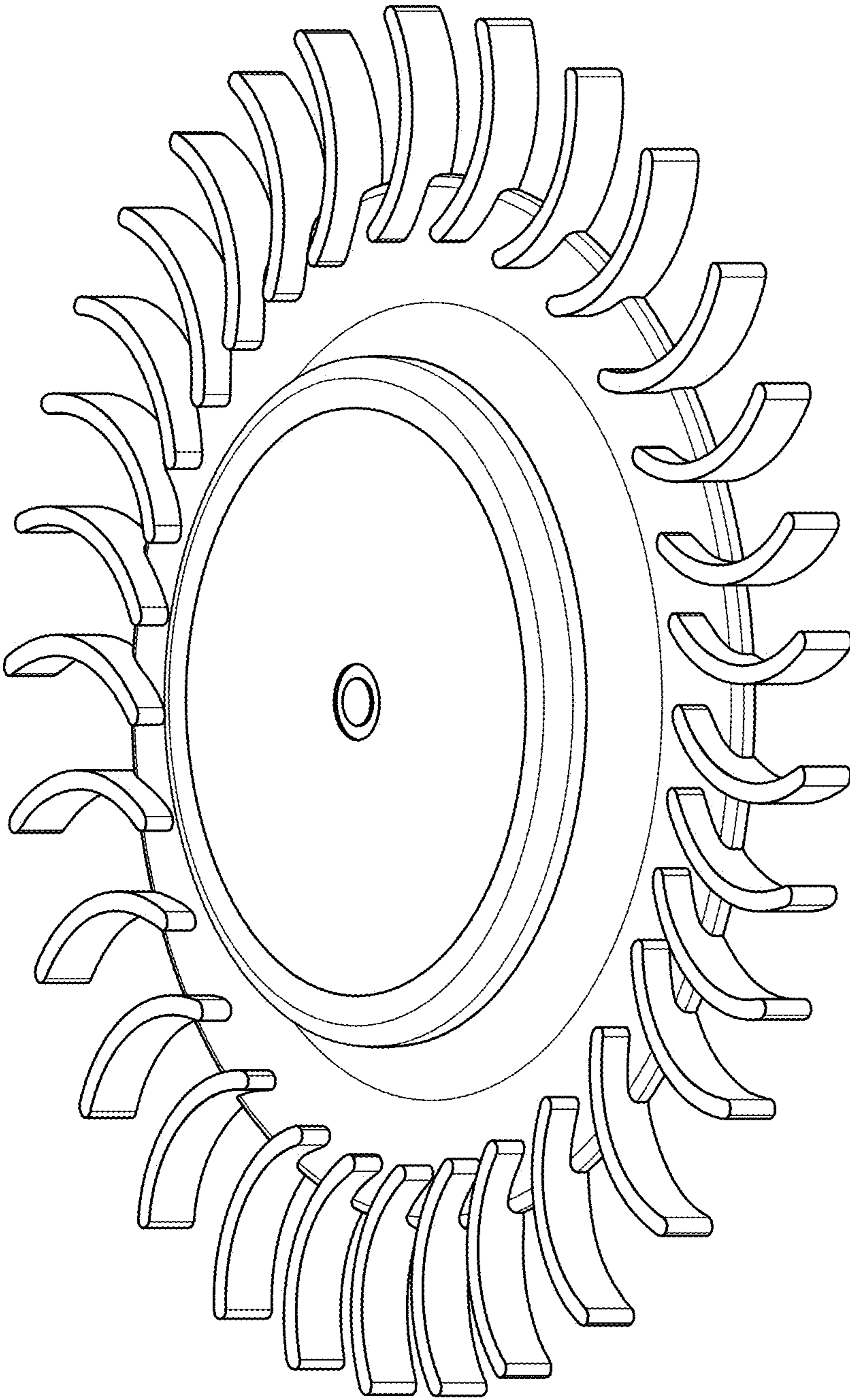
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**Fig. 1**

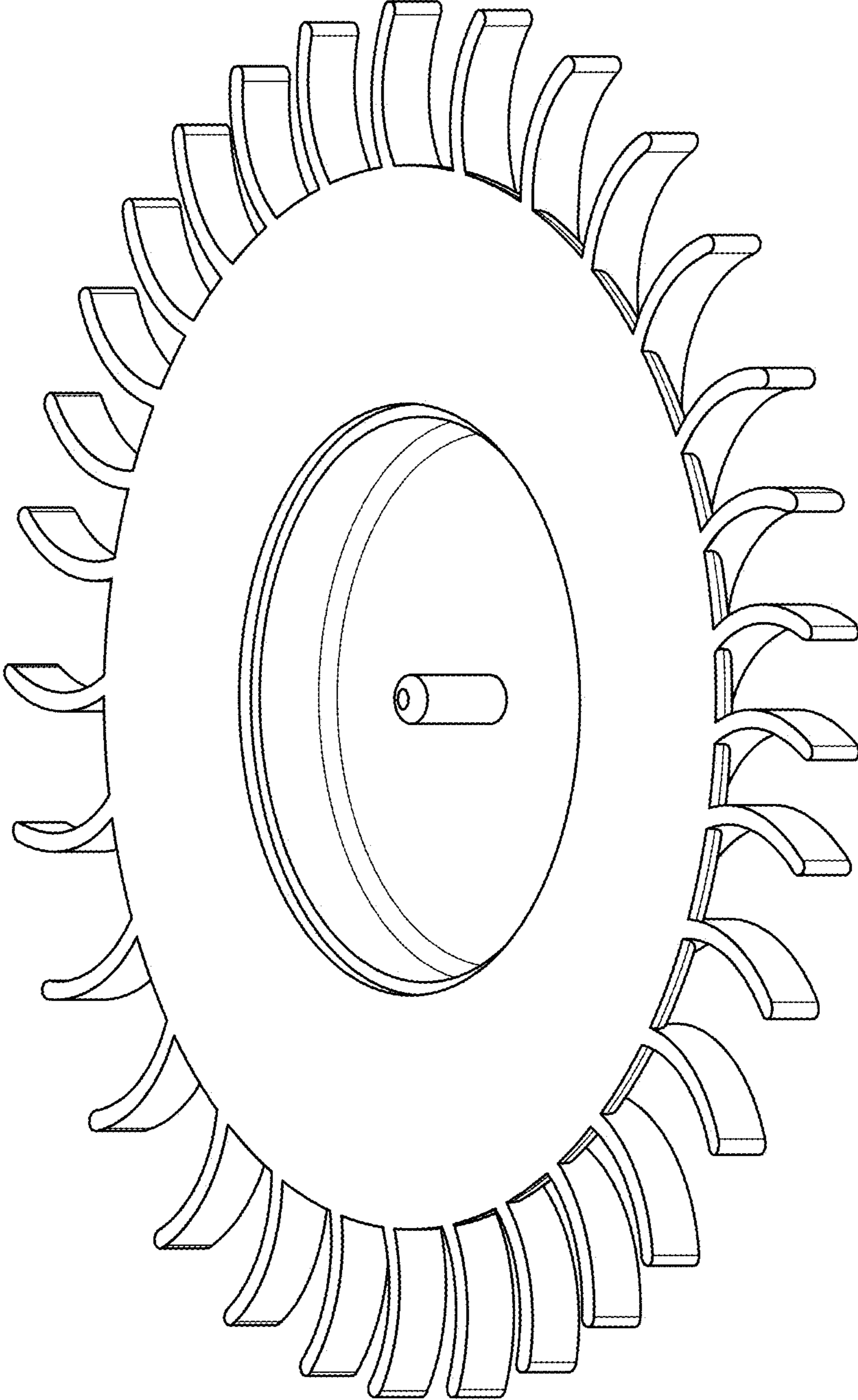
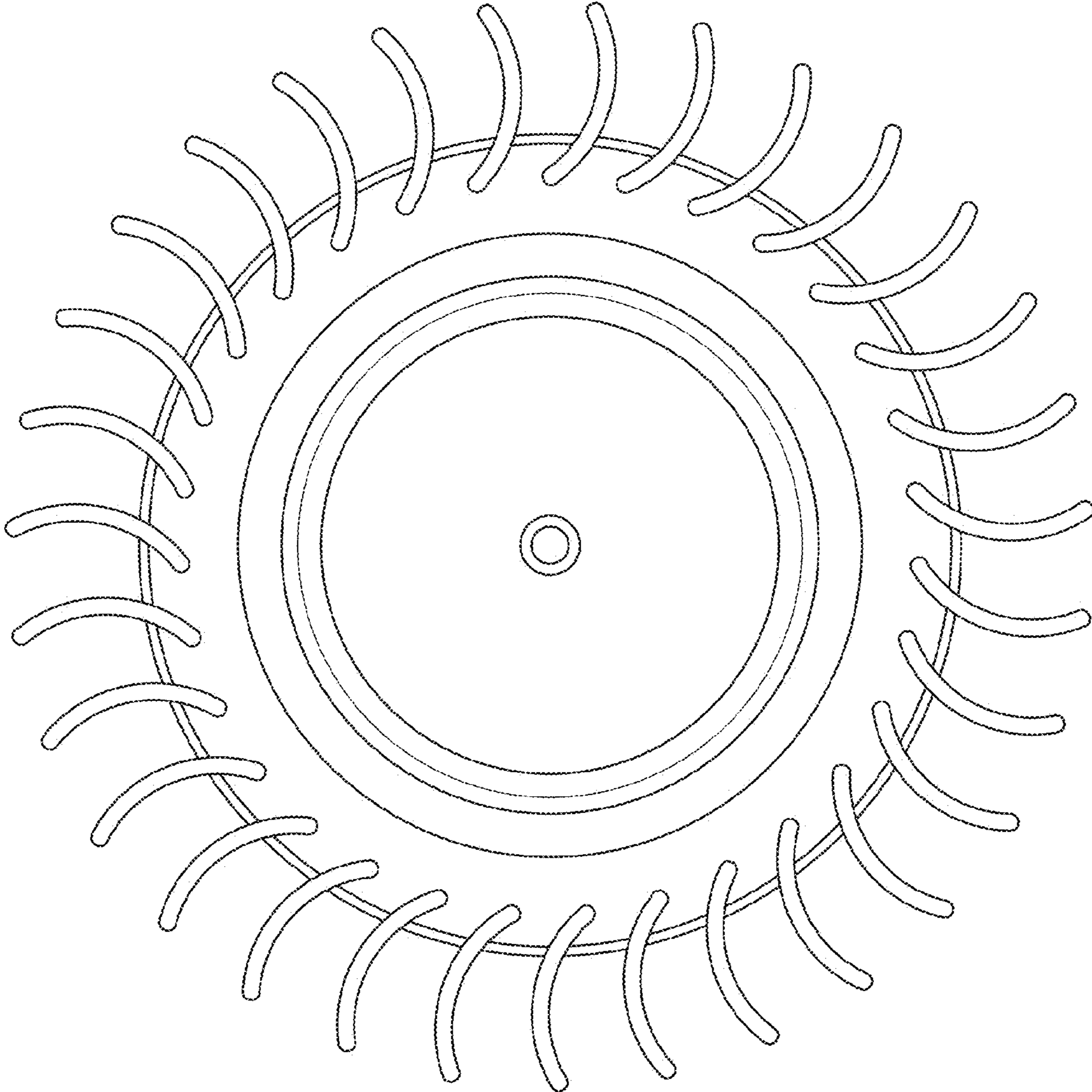
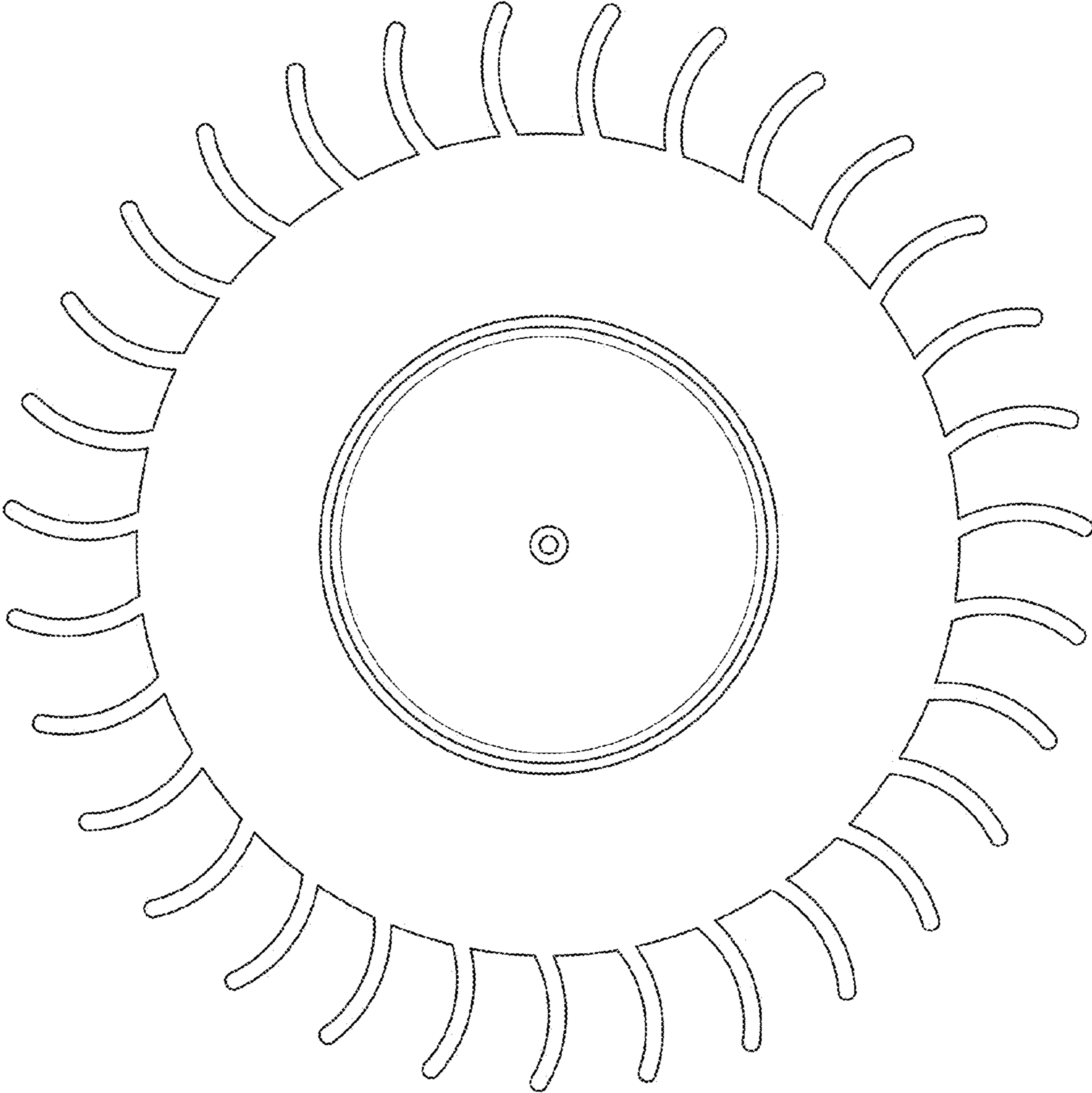


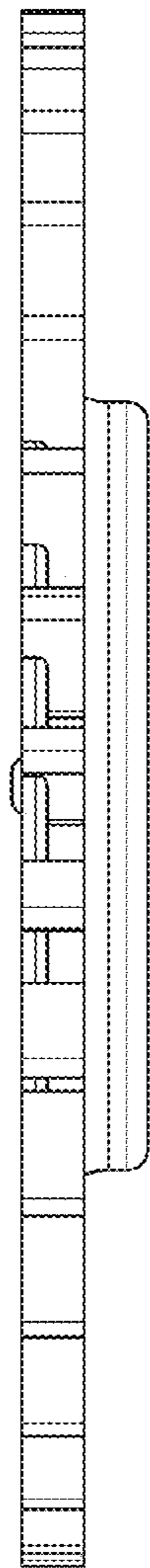
Fig. 2



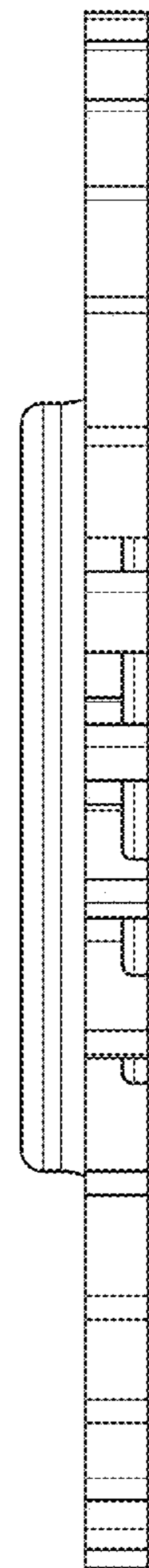
**Fig. 3**



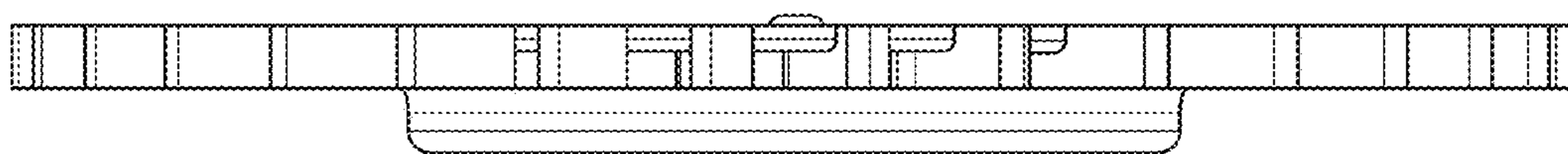
**Fig. 4**



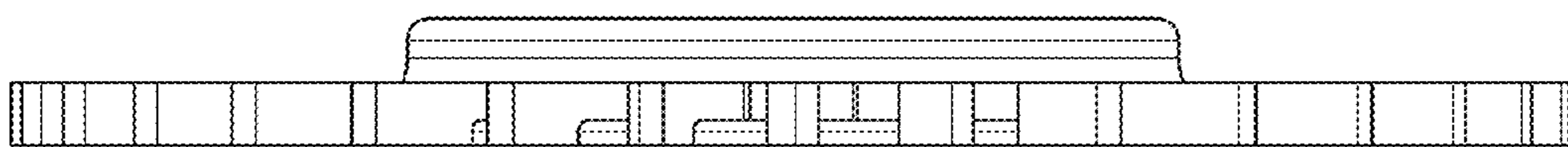
*Fig. 5*



*Fig. 6*



*Fig. 7*



*Fig. 8*